	DBs
1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
2	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
5	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
6	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
7	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
8	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
9	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
12	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
13	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
14	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
15	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
16	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB

	Ref #	Search Text
17	S17	S5 same S6
18	S18	S8 and S16 and S17
19	S19	("4742385" | "4827082" | "5027191" | "5311402").PN.
20	S20	("2005/0189632").URPN.
21	S21	("4603345" | "5032894" | "5281852" | "5324687" | "5401688" | "5410451" | "5448511" | "5459641" | "5552963").PN.
22	S22	("5776797").URPN.
23	S23	("5133495" | "5229916" | "5281852" | "5394303" | "5397916" | "5582326" | "5679977" | "5682061" | "5714405" | "5776797" | "5801446" | "5885549" | "5895970").PN.
24	S24	(bond$3 seal$3) near6 (die substrate S3)
25	S25	S5 with S24
26	S26	S7 same S25
27	S27	S2 same S25
28	S28	S25 with (via cavity opening)
29	S29	S2 same S28
30	S30	encapsulant near4 filler
31	S31	(silicone or polymer) with S30
32	S32	S31 and (@ad<"20040301" @rlad<"20040301")
33	S33	S31 same glob

	DBs
17	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
18	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
19	US-PGPUB; USPAT; USOCR
20	USPAT
21	US-PGPUB; USPAT; USOCR
22	USPAT
23	US-PGPUB; USPAT; USOCR
24	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
25	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
26	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
27	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
28	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
29	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
30	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
31	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
32	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
33	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB

	Ref #	Search Text
1	S1	("seal$3encapsulat$3").PN.
2	S2	seal$3 encapsulat$3
3	S3	((S1 adj2 "D") or (three near3 dimension$3)) near6 ((metal near3 bond$3 near4 ("ic" or (integrated near3 circuit))) or (bond$3 near4 ("ic" or (integrated near3 circuit))) or (("ic" or (integrated near3 circuit))))
4	S4	connector (control$3 near3 collaps$4 near3 chip) "C4" (solder near3 (ball bump))
5	S5	(contact near3 pad) (copper near3 (contact or pad))
6	S6	(bond$3 seal$3) near6 (die substrate)
7	S7	S5 with S6
8	S8	S2 same S3
9	S9	S2 with S3
10	S10	die substrate
11	S11	die substrate wafer
12	S12	S4 with S10
13	S13	S4 with S11
14	S14	S13 and S9 and S7
15	S15	S13 and S9
16	S16	S4 same S11